

*Supply of a flip chip bonder*

**Award criteria**

The awarding of the supply will take place on the basis of the criterion of the most economically advantageous offer pursuant to art. 95, par. 2, Decreto Legislativo (hereafter d. lgs.) 50.16.

The economic offers above the base of the tender and / or delivery times of more than 7 months, as specified in the Technical specifications (par. 5.4), will be excluded from the evaluation.

The Commission of selection, established pursuant to art. 77 of d. lgs. 50.16, will have the opportunity to evaluate offers up to 100 points, of which 70 maximum for technical evaluation and delivery times, and a maximum of 30 for economic evaluation.

The attribution of the scores will be performed using the aggregative-compensator method and based on the following formula:

$$C(a) = \sum_h (W_h \cdot V_h(a))$$

where it is:

- C(a) evaluation index of the 'a' offer;
- h total number of requirements;
- W<sub>h</sub> maximum score attributed to the 'h' requirement;
- V<sub>h</sub>(a) performance coefficient of the offer 'a' related to the 'h' requirement, variable between 0 and 1.

For the calculation of the coefficients V<sub>h</sub>(a) will be used the following formulas.

*Price*

$$V_h(a) = 0.9 \frac{R_a}{R_{thr}} \quad \text{for } R_a \leq R_{thr}$$

$$V_h(a) = 0.9 + 0.1 \frac{R_a - R_{thr}}{R_{MAX} - R_{thr}} \quad \text{for } R_a > R_{thr}$$

where it is:

- R<sub>a</sub> discount offered by the competitor 'a';
- R<sub>MAX</sub> most convenient discount;
- R<sub>thr</sub> arithmetic average of the discounts of competitors' offers.



Time

$$V_h(a) = \frac{R_{\min}}{R_a}$$

where it is:

- $R_a$  time offered by the competitor 'a';
- $R_{\min}$  minimum time.

Number

$$V_h(a) = \frac{R_a}{R_{\text{best}}}$$

where it is:

- $R_a$  number offered by the competitor 'a';
- $R_{\text{best}}$  largest number.

The maximum  $W_h$  scores assigned to the evaluation elements are listed in Tab. 1: the total of 100 points is composed by a maximum of 30 points for the economic evaluation, a maximum of 20 for the delivery times and 50 for the evaluation of the technical specifications.

The characteristics subject to technical evaluation, shown in Tab. 1, are intended to supplement the minimum requirements listed in Technical specifications (cha. 6). The absence of these characteristics does not imply the rejection of the offer.

Feature	Evaluation parameter	Score
Price		30
Delivery time (7 months maximum from contract signature)		20
Technical features		50
10" wafer management (in addition to 6" and 8")	Presence	5
Number of dice/min (positioning) in excess to 40 (10 $\mu\text{m}$ positioning resolution)	Frequency	20
Multiple bonding-head	Presence	10
Bonding rate (positioning time excluded) in thermo-compression/eutectic-bonding	Frequency	15

Tab. 1: Scores for offer evaluation

The scores indicated in Tab. 1 are intended as maximum scores attributable for each characteristic.

The person responsible for the procedure

(Paolo De Remigis)